



## RoHS3 Certificate of Compliance

This is to certify that all the parts listed in Annex-1 below are RoHS3 compliant and meet the requirements of the current EU RoHS Directive 2015/863/EU.

<b>Substance</b>	<b>Maximum Control Value</b>
Lead	0.1% by weight (1000 ppm)
Mercury	0.1% by weight (1000 ppm)
Cadmium	0.01% by weight (100 ppm)
Hexavalent Chromium	0.1% by weight (1000 ppm)
Polybrominated Biphenyls (PBB)	0.1% by weight (1000 ppm)
Polybrominated Diphenyl Ethers (PBDE)	0.1% by weight (1000 ppm)
DBP	0.1% by weight (1000 ppm)
BBP	0.1% by weight (1000 ppm)
DEHP	0.1% by weight (1000 ppm)
DIBP	0.1% by weight (1000 ppm)

**Coreworks Product Name: Inductors**

### Authorized signatory

Signature: 

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**Annex-1**

**RoHS Compliance by Part Number**

<b>Part Number</b>	<b>Description</b>	<b>Exemptions</b>
RT -Series	Thin Film Chip Inductor	None
SM-F Series	Multilayer Chip Inductor	None
XM-Series	Wire Wound Chip Inductor	None
XMM-Series	Wire Wound Chip Inductor	None
LKI-Series	Multilayer Chip Bead	None
LKI-Series	Multilayer Chip Beads	None
SPO-Series	SMD Power Inductor	None
SPM-Series	Shielded SMD Power Inductor	None
FCG-Series	Multilayer Ferrite Chip Inductor	None
FCG-G Series	Multilayer Ferrite Chip Inductor	None
LWG-Series	Wire Wound Chip Inductor(Ferrite /Open Type)	None
FCP-Series	Wire Wound Type Power Inductor	None
XLPS-A-Series	Thin Film Chip Inductor (Auto grade)	None
XLPS-Series	Thin Film Chip Inductor (Commercial grade)	None
LMG-Series	Non-shielded, High Power, Wire Wound Power Inductor	None
XLPF-Series	Shielded SMD Power Inductor	None
XLPC-Series	Power Choke Power Inductor	None
SFW-Series	Non-shielded, High Power, Wire Wound Power Inductor	None